

#### Important notice

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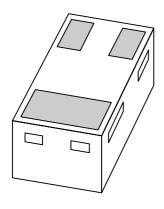
If you have any questions related to the data sheet, please contact our nearest sales office via e-mail or telephone (details via **salesaddresses@nexperia.com**). Thank you for your cooperation and understanding,

Kind regards,

Team Nexperia

# **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# **BAT54CM**Schottky barrier double diode

Product data sheet 2003 Nov 11



# Schottky barrier double diode

#### **BAT54CM**

#### **FEATURES**

- · Low forward voltage
- Leadless ultra small plastic package  $(1.0 \times 0.6 \times 0.5 \text{ mm})$
- Boardspace 1.17 mm<sup>2</sup> (approx. 10% of SOT23)
- Power dissipation comparable to SOT23.

#### **APPLICATIONS**

- Ultra high-speed switching
- Voltage clamping
- · Protection circuits
- Mobile communications, digital (still) cameras, PDAs and PCMCIA cards.

#### **DESCRIPTION**

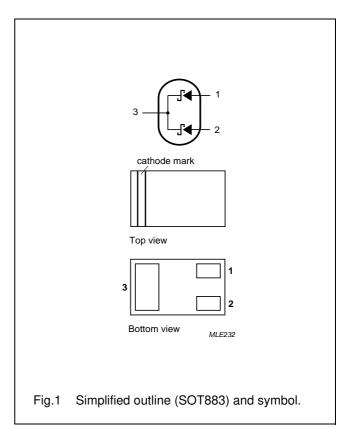
Planar Schottky barrier double diode encapsulated in a SOT883 leadless ultra small plastic package.

#### **MARKING**

TYPE NUMBER	MARKING CODE
BAT54CM	S3

#### **PINNING**

PIN	DESCRIPTION	
1	anode (a <sub>1</sub> )	
2	anode (a <sub>2</sub> )	
3	common cathode	



#### **ORDERING INFORMATION**

TYPE NUMBER	PACKAGE		
TIPE NOMBER	NAME DESCRIPTION		VERSION
BAT54CM	_	leadless ultra small plastic package; 3 solder lands; body $1.0 \times 0.6 \times 0.5 \text{ mm}$	SOT883

# Schottky barrier double diode

BAT54CM

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>R</sub>	continuous reverse voltage		_	30	٧
I <sub>F</sub>	continuous forward current		_	200	mA
I <sub>FRM</sub>	repetitive peak forward current	$t_p \le 1 \text{ s}; \delta \le 0.5$	-	300	mA
I <sub>FSM</sub>	non-repetitive peak forward current	t <sub>p</sub> < 10 ms	-	600	mA
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		-	150	°C
P <sub>tot</sub>	total power dissipation (per package)	T <sub>amb</sub> ≤ 25 °C; note 1	-	250	mW

#### Note

1. Refer to SOT883 standard mounting conditions (footprint); FR4 with 60 μm copper strip line.

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Refer to SOT883 standard mounting conditions (footprint), FR4 with 60 μm copper strip line.

#### **Soldering**

Reflow soldering is the only recommended soldering method.

#### **ELECTRICAL CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
Per diode				
V <sub>F</sub>	forward voltage	see Fig.2;		
		$I_F = 0.1 \text{ mA}$	240	mV
		I <sub>F</sub> = 1 mA	320	mV
		$I_F = 10 \text{ mA}$	400	mV
		$I_F = 30 \text{ mA}$	500	mV
		$I_F = 100 \text{ mA}$	800	mV
I <sub>R</sub>	continuous reverse current	V <sub>R</sub> = 25 V; note 1; see Fig.3	2	μΑ
C <sub>d</sub>	diode capacitance	f = 1 MHz; V <sub>R</sub> = 1 V; see Fig.4	10	pF

#### Note

1. Pulsed test:  $t_p \le 300~\mu s;~\delta \le 0.02.$ 

# Schottky barrier double diode

# BAT54CM

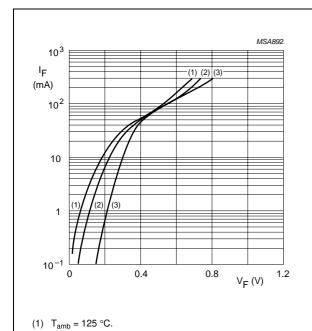
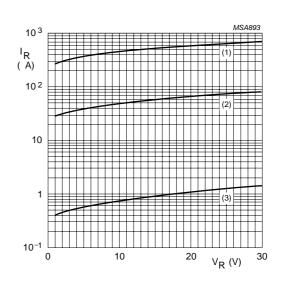


Fig.2 Forward current as a function of forward voltage; typical values.

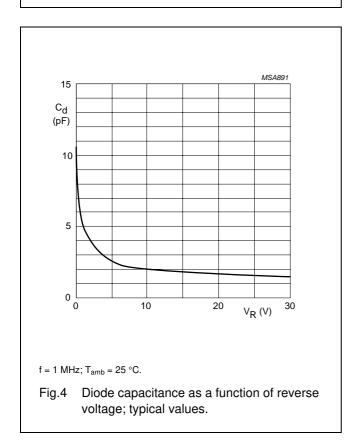
(2)  $T_{amb} = 85 \, ^{\circ}C$ .

(3)  $T_{amb} = 25 \, ^{\circ}C$ .



- (1)  $T_{amb} = 125 \, ^{\circ}C$ .
- (2)  $T_{amb} = 85 \, ^{\circ}C$ .
- (3)  $T_{amb} = 25 \, ^{\circ}C$ .

Fig.3 Reverse current as a function of reverse voltage; typical values.



# Schottky barrier double diode

BAT54CM

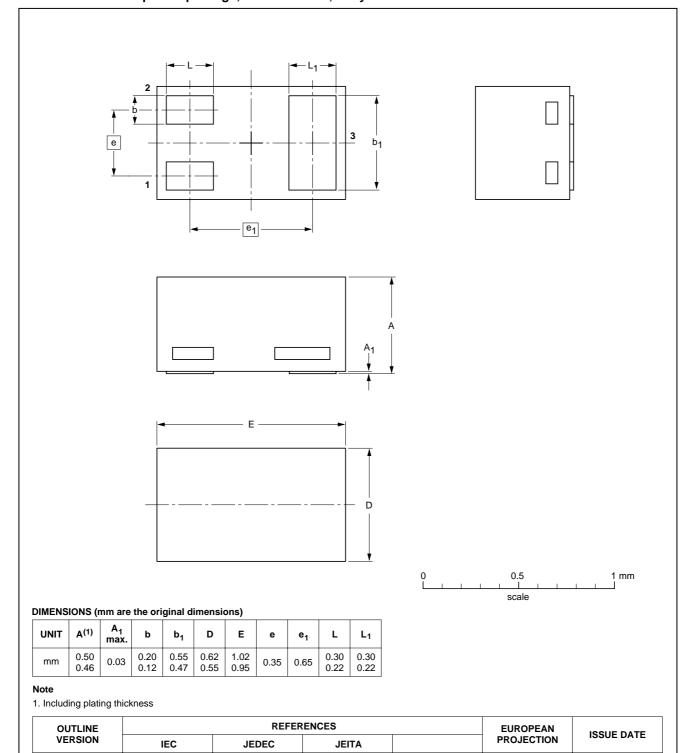
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#### **PACKAGE OUTLINE**

Leadless ultra small plastic package; 3 solder lands; body 1.0 x 0.6 x 0.5 mm

**SOT883** 



SC-101

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SOT883

### Schottky barrier double diode

BAT54CM

#### **DATA SHEET STATUS**

DOCUMENT STATUS(1)	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
- 2. The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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# **NXP Semiconductors**

#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors. No changes were made to the content, except for the legal definitions and disclaimers.

#### **Contact information**

For additional information please visit: http://www.nxp.com

For sales offices addresses send e-mail to: salesaddresses@nxp.com

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